



Bill of Materials

TI DESIGNS

Part #

Literature #

DESIGNATOR	QUANTITY	VALUE	DESCRIPTION	SIZE	PART NUMBER	MANUFACTURER
U1	1	OPA615	Wide Bandwidth, DC Restoration Circuit	SO-14	OPA615ID (Rails, 50)	TI
					OPA615IDR (Tape and Reel, 2500)	TI
C6	1	22pF	Capacitor, Ceramic, 50V, NP0, 5%	0603	Std	Std
R3,R4,R9	3	300	Resistor, Chip, 1/16W, 1%	0603	Std	Std
R5,R11	2	100	Resistor, Chip, 1/16W, 1%	0603	Std	Std
R1,R6,R10	3	49.9	Resistor, Chip, 1/16W, 1%	0603	Std	Std
R2	1	124	Resistor, Chip, 1/16W, 1%	0603	Std	Std
R7,R8	2	0	Resistor, Chip, 1/16W, 1%	0603	Std	Std
C1,C2	2	2.2uF	Capacitor, Tantalum, 16V, X7R, 10%	0805	Std	Std
C3,C4	2	0.1uF	Capacitor, Ceramic, 16V, X7R, 10%	0603	Std	Std
C5	1	0.1uF	Capacitor, Ceramic, 16V, X7R, 10%	0805	Std	Std
L1,L2	2		Emi-Suppression Ferrite Chip (populate with 0R if not desired)	0805	1206 B 900 R	Steward Li
In,Hold,E_Out,C_Out	4		SMA or SMB Board Jack		142-0701-801	Johnson
TB	1		Terminal Block, 2.5mm Centers		ED555/3DS	On-Shore

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